

#### IN THE ABSTRACT

*Please amend the paragraph of the ABSTRACT OF THE DISCLOSURE, which begins at line 5 on page 16 of the present application, in accordance with the following replacement paragraph:*

An improved damascene method of forming a write coil of a magnetic head. The method includes the steps of forming a hard mask layer over an insulator layer; forming a photoresist layer over the hard mask layer; performing an image patterning process to produce a write coil pattern in the photoresist layer; etching to remove portions of the hard mask layer in accordance with the write coil pattern; etching to remove portions of the insulator layer in accordance with the write coil pattern; etching to remove the remaining portion of the etched hard mask layer; after removing the etched hard mask layer, electroplating a material ~~comprising copper (Cu)~~ within the etched portion of the insulator material; and performing a chemical-mechanical polishing (CMP) process over the ~~resulting structure~~ electroplated material. By removing the remainder of the hard mask material before the CMP, the quality of the CMP is improved. ~~Although any suitable hard mask material may be utilized, if the insulator layer is a hard baked resist then Ta<sub>2</sub>O<sub>5</sub> having a relatively high selectivity, low brittleness, and improved adhesion is preferred as the hard mask material.~~